

PRELIMINARY SPEC

Part Number: AM27SECK08

Super Bright Orange

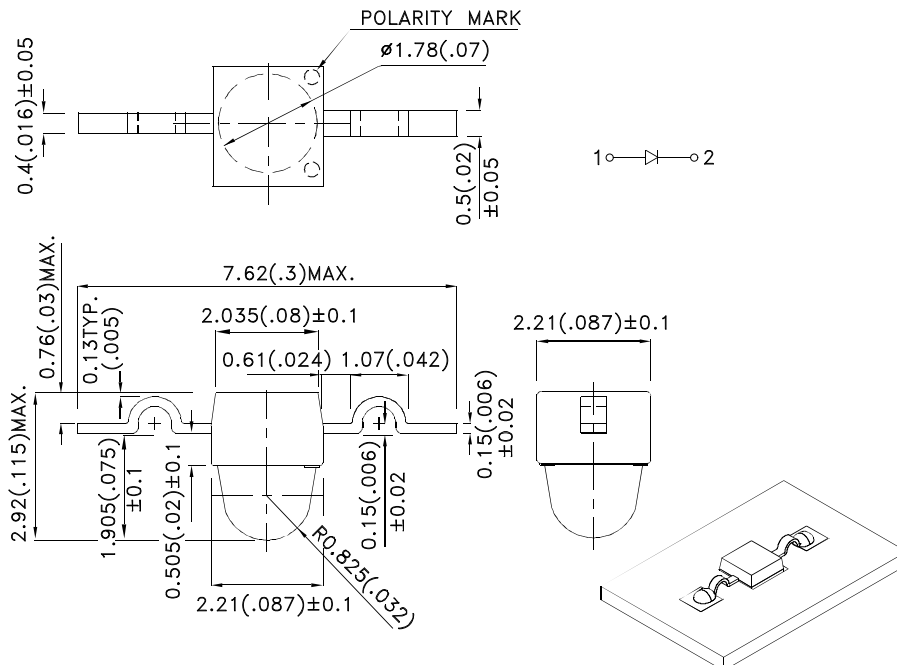
Features

- Subminiature package.
- Yoke lead.
- Long life - solid state reliability.
- Low package profile.
- Package :1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Super Bright Orange device is made with InGaAlP (on GaAs substrate) light emitting diode chip.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ " unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.
5. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
AM27SECK08	Super Bright Orange (InGaAlP)	WATER CLEAR	900	1800	20°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Super Bright Orange	610		nm	I _F =20mA
λ _D [1]	Dominant Wavelength	Super Bright Orange	601		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Super Bright Orange	29		nm	I _F =20mA
C	Capacitance	Super Bright Orange	15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Super Bright Orange	2.1	2.5	V	I _F =20mA
I _R	Reverse Current	Super Bright Orange		10	uA	V _R =5V

Notes:

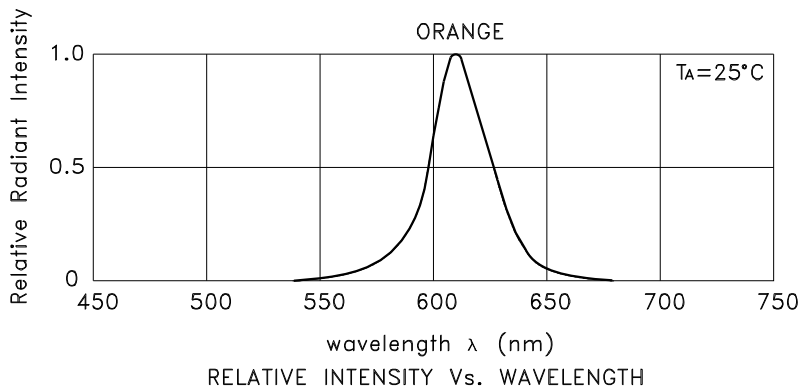
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

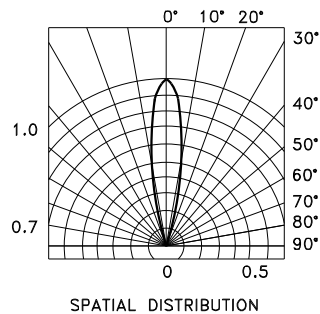
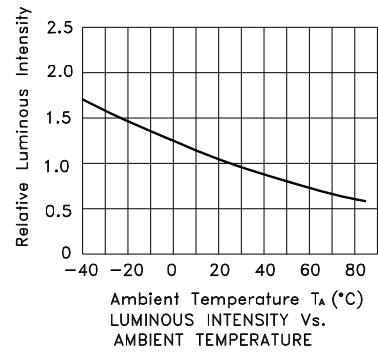
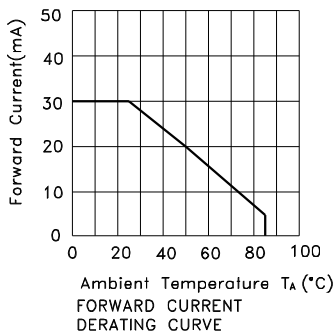
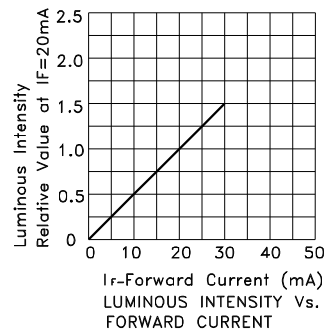
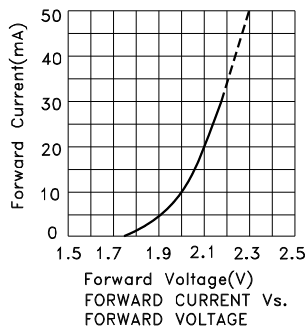
Parameter	Super Bright Orange	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

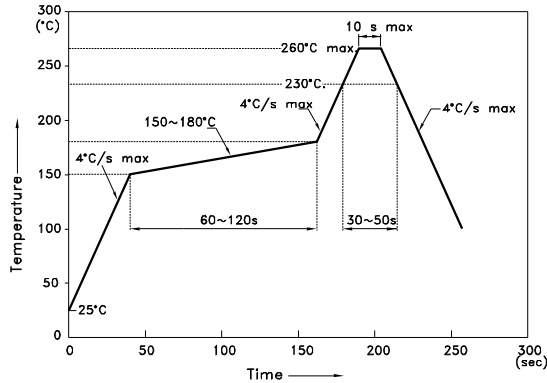


Super Bright Orange AM27SECK08



AM27SECK08

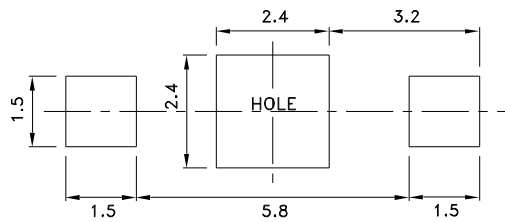
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Tape Specifications (Units : mm)

